

Attorney Docket No.: NECW 18.159

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor: Atsushi NISHIZAWA

Serial No.: 09/751,979

Filed: December 29, 2000

Title: MANUFACTURING METHOD OF SEMICONDUCTOR
INTEGRATED CIRCUIT INCLUDING SIMULTANEOUS
FORMATION OF VIA HOLE REACHING METAL WIRING
AND CONCAVE GROOVE IN INTERLAYER FILM AND
SEMICONDUCTOR INTEGRATED CIRCUIT MANUFACTURED
WITH THE MANUFACTURING METHOD

Examiner: George A. Goudreau

Group Art Unit: 1763

Assistant Commissioner for Patents
Washington, D.C. 20231

FAX RECEIVED

NOV 19 2002

GROUP 1700

CHANGE IN CORRESPONDENCE ADDRESS

SIR:

It is respectfully requested that any future correspondence regarding the above-referenced application be directed to Applicant's attorneys (previously appointed) at the following new correspondence address:

Katten Muchin Zavis Rosenman
575 Madison Avenue
New York, New York 10022
Phone: (212) 940-8800
Fax: (212) 940-8986 or (212) 940-8987

Any inquiries regarding this change in address may be directed to the Applicant's undersigned attorney at the above-referenced telephone numbers.

Our CUSTOMER NUMBER 026304 remains the same.


Respectfully submitted,

Michael I. Markowitz
Reg. No. 30,659

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